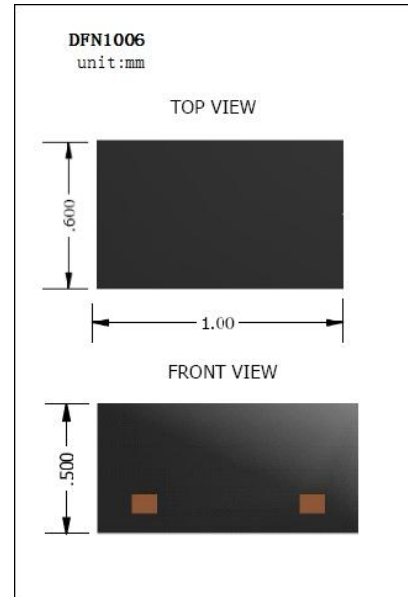
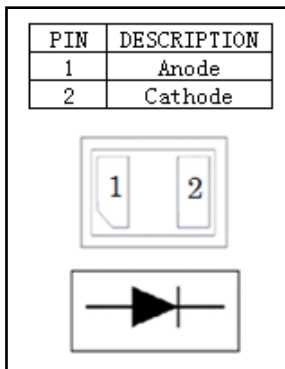


DATA SHEET

BZX884C2V4 THRU BZX884C75

- ◇ Planar Die construction
- ◇ 250mW Power Dissipation
- ◇ Zener Voltages from 2.4V–75V
- ◇ RoHS compliant / Green EMC



MAXIMUM RATINGS (Ta = 25 °C)

Symbol	Parameter	Value	Units
V _F	Maximum Forward Voltage @ IF=10mA	0.9	V
P _(AV)	Power Dissipation	250	mW
T _J , T _{stg}	Operating And Storage Temperature	-55 to 150	°C
I _{FSM}	Peak Forward Surge Current	2.0	A
T _{stg}	Storage Temperature Range	-55 to 150	°C
R _j	Thermal Resistance Junction to Ambient	417	°C/W

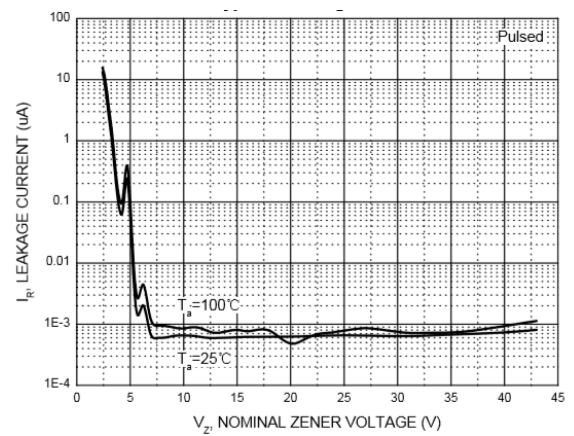
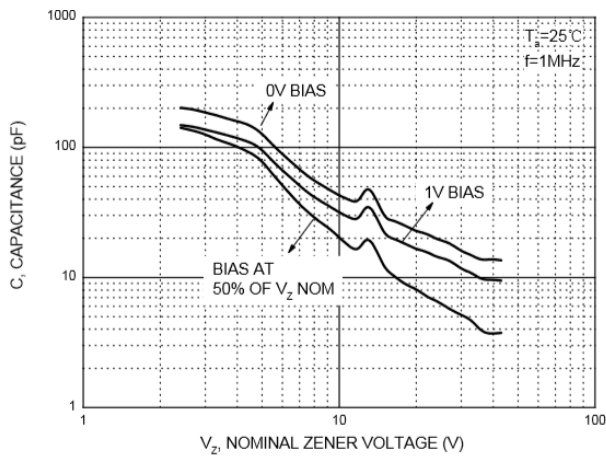
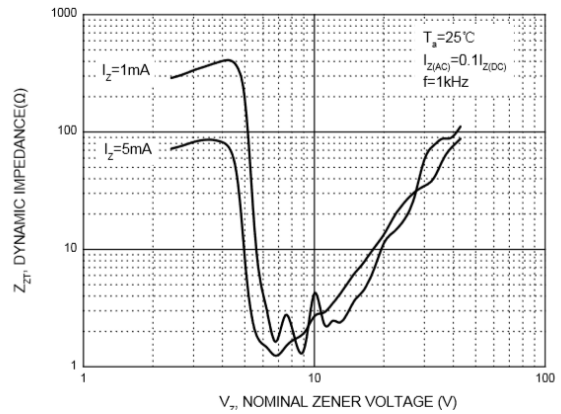
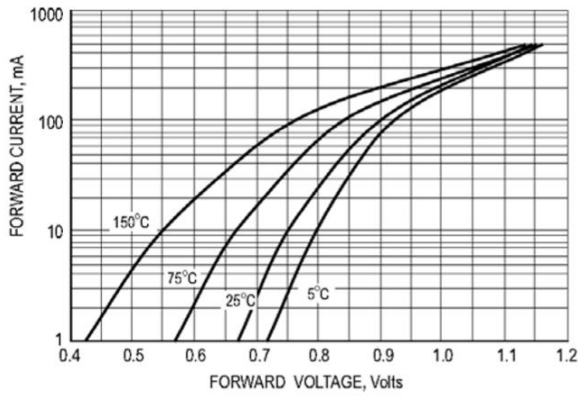
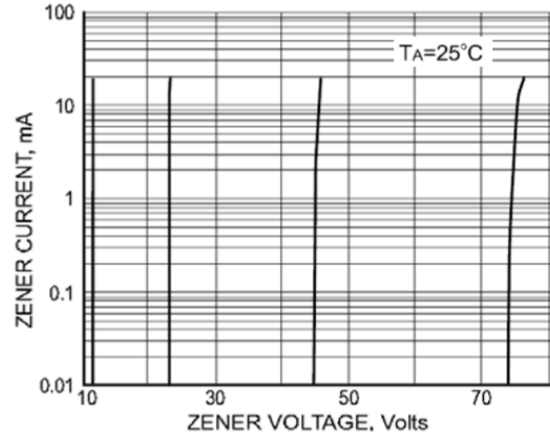
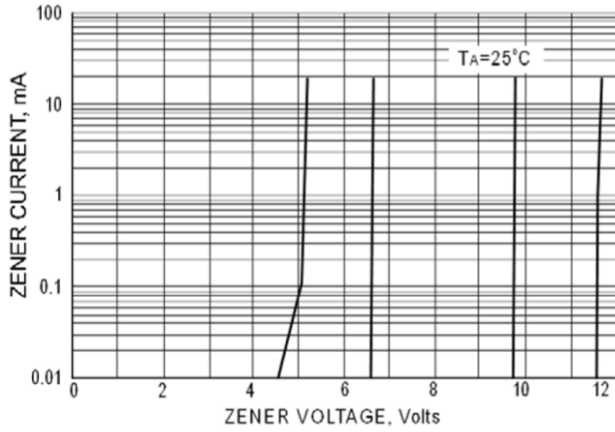
ELECTRICAL CHARACTERISTICS (Ta = 25 °C unless otherwise noted)

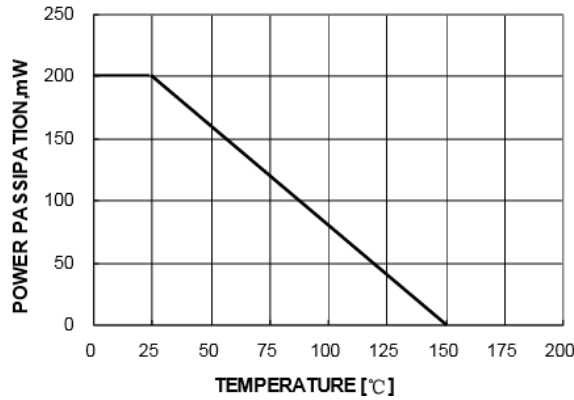
Type	Device	V _Z (V) *1			I _{ZT}	Z _{ZT} @I _{ZT}	Z _{ZK} @I _{ZK}	I _{ZK}	I _R	V _R
		Nom(V)	Min(V)	Max(V)						
BZX884C2V4	B1	2.4	2.28	2.52	5	100	400	1	50	1
BZX884C2V7	B2	2.7	2.57	2.84	5	100	450	1	20	1
BZX884C3V0	B3	3	2.85	3.15	5	95	500	1	10	1
BZX884C3V3	B4	3.3	3.14	3.47	5	95	500	1	5	1
BZX884C3V6	B5	3.6	3.42	3.78	5	90	500	1	5	1
BZX884C3V9	B6	3.9	3.71	4.1	5	90	500	1	3	1
BZX884C4V3	B7	4.3	4.09	4.52	5	90	600	1	3	1

Type	Device	V _Z (V) * ¹			I _{ZT}	Z _{ZT} @I _{ZT}	Z _{ZK} @I _{ZK}	I _{ZK}	I _R	V _R
Number	Marking	Nom(V)	Min(V)	Max(V)	mA	Ω		(mA)	(uA)	(V)
BZX884C4V7	B8	4.7	4.47	4.94	5	80	500	1	3	2
BZX884C5V1	B9	5.1	4.85	5.36	5	60	480	1	2	2
BZX884C5V6	BA	5.6	5.32	5.88	5	40	400	1	1	2
BZX884C6V2	BB	6.2	5.89	6.51	5	10	150	1	3	4
BZX884C6V8	BC	6.8	6.46	7.14	5	15	80	1	2	4
BZX884C7V5	BD	7.5	7.13	7.88	5	15	80	1	1	5
BZX884C8V2	BE	8.2	7.79	8.61	5	15	80	1	0.7	5
BZX884C9V1	BF	9.1	8.65	9.56	5	15	100	1	0.5	6
BZX884C10	BG	10	9.5	10.5	5	20	150	1	0.2	7
BZX884C11	BH	11	10.45	11.55	5	20	150	1	0.1	8
BZX884C12	BJ	12	11.4	12.6	5	25	150	1	0.1	8
BZX884C13	BK	13	12.35	13.65	5	30	170	1	0.1	8
BZX884C15	BL	15	14.25	15.75	5	30	200	1	0.05	10.5
BZX884C16	D1	16	15.2	16.8	5	40	200	1	0.05	11.2
BZX884C18	D2	18	17.1	18.9	5	45	225	1	0.05	12.6
BZX884C20	D3	20	19	21	5	55	225	1	0.05	14
BZX884C22	D4	22	20.9	23.1	5	55	250	1	0.05	15.4
BZX884C24	D5	24	22.8	25.2	5	70	250	1	0.05	16.8
BZX884C27	D6	27	25.65	28.35	2	80	300	0.5	0.05	18.9
BZX884C30	D7	30	28.5	31.5	2	80	300	0.5	0.05	21
BZX884C33	D8	33	31.35	34.65	2	80	325	0.5	0.05	23.1
BZX884C36	D9	36	34.2	37.8	2	90	350	0.5	0.05	25.2
BZX884C39	DA	39	37.05	40.95	2	130	350	0.5	0.05	27.3
BZX884C43	DB	43	40.85	45.15	2	150	375	0.5	0.05	30.1
BZX884C47	DD	47	44.65	49.35	2	170	375	0.5	0.05	32.9
BZX884C51	DD	51	48.45	53.55	2	180	400	0.5	0.05	35.7
BZX884C56	DE	56	53.2	58.8	2	200	425	0.5	0.05	39.2
BZX884C62	DF	62	58.9	65.1	2	215	450	0.5	0.05	43.4
BZX884C68	DG	68	64.6	71.4	2	240	475	0.5	0.05	47.6
BZX884C75	DH	75	71.25	78.75	2	255	500	0.5	0.05	52.5

*¹ Pulse width = 10 ms

Typical Characteristics



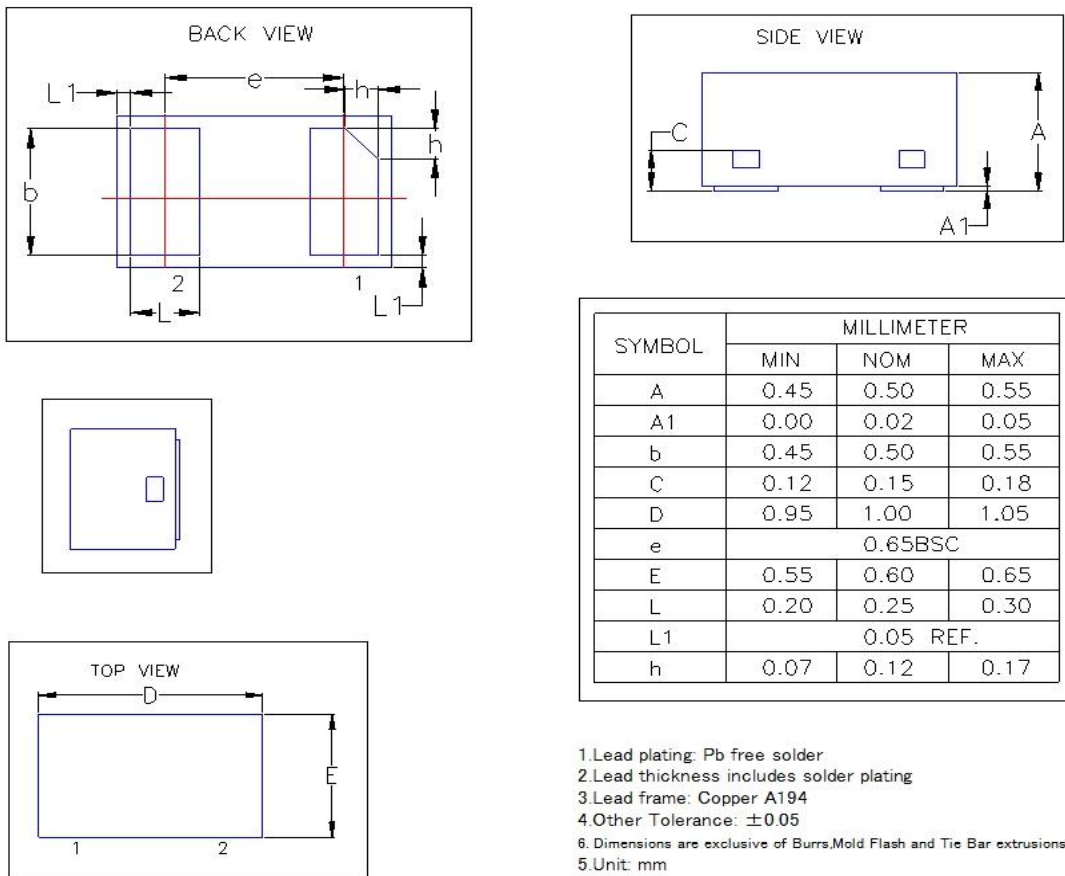


ORDERING INFORMATION

Device	Package	Shipping	Tape wide	Emboss pitch	Tape specification	Notes
BZX884C2V4- BZX884C75	DFN1006	Tape & Reel 10000pcs /7" Reel	8mm	4mm	Conductive	

PACKAGE DIMENSIONS

Package outline : DFN1006



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	0.45	0.50	0.55
A1	0.00	0.02	0.05
b	0.45	0.50	0.55
C	0.12	0.15	0.18
D	0.95	1.00	1.05
e	0.65BSC		
E	0.55	0.60	0.65
L	0.20	0.25	0.30
L1	0.05 REF.		
h	0.07	0.12	0.17

1. Lead plating: Pb free solder
2. Lead thickness includes solder plating
3. Lead frame: Copper A194
4. Other Tolerance: ± 0.05
6. Dimensions are exclusive of Burrs, Mold Flash and Tie Bar extrusions
5. Unit: mm